**RESUME**

H.No. 222,Rudra Ward,

 In Front of Nagar Palika Office,Gotegaon

 Dist:Narsinghpur (M.P.) 487118

 **Mobile No.:** 9302859065 ;8770619624

**SHUBHAM SAHU Email**:sahushubham093@gmail.com

OBJECTIVE:

I want a highly rewarding career where I can use my skills and knowledge for organizational and personal growth.

EDUCATIONAL QUALIFICATIONS:

B.E(Hons) in Industrial&Production Engineering Discipline at JEC with CGPA 7.61

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| S.No. | Examination | College/School | Year | CGPA/Percentage |
| 1 | B.E. | JABALPUR ENGIINEERING COLLEGE,JBP | 2018 | 7.61 |
| 2 | XII | VIDYA VIJAY BAL MANDIR,INDORE | 2013 | 81.40 |
| 3 | X | SHRI BALAJI PUBLIC SCHOOL,JBP | 2011 | 88.83 |

TECHNICAL SKILLS:

 Subject : Indian History,Indian Constitution,

 General Knowledge of Madhya Pradesh,

 Indian Geography.

 Extra Skills : Customer Relationship & Negotiation Skills.

 Management Skills.

PROJECT:

* Rotary Sand Seiving Machine Feb’2017- May’2017

-Seperation of Fine Sand And Grables

* Calculation of Average Surface Texture Jan’2018-April’2018

-Determination of Surface Roughness of Shaft with the help of Artificial Nueral Network

INDUSTRIAL EXPERIENCE:

 Internship

* Bharat Heavy Electricals Limited(BHEL),Bhopal(M.P). May’29-June’10

 -Worked at Production Department of Turbine Shop

* Badve Engineering Limited,Pithampur Indore June’6-June’20

 -In Mechanical Department & Paint Shop,J-103 Centuro Frame Line Manufacturing

AWARDS/ACHIEVEMENTS:

* Secured First Rank in Poster Making Competition organised by Karwaan.
* Awarded with Amul Vidya Bhusan & Amul Vidya Shree for academics in M.P Board
* Awarded with Silver Medal for securing 2nd Rank in 10th M.P Board.
* Attempted 2018 Prelims(Qualified)and 2019 MPPSC Prelims with score !50.

EXTRA- CURRICULUM:

* Co-ordinator at Aureole,JEC.
* Secertary in Event Organisation Committee.
* Member at Yogoda Satsang Society

DECLARATION :

I hereby declare that all above information is true to the best of my knowledge and belief.

Date& Place: Signature: